III. CLAIM AMENDMENTS

1. (Currently Amended) A semiconductor substrate holding apparatus comprising [[cassette reducer for reducing]] a substrate holder capable of holding a substrate of a predetermined size, and [[the]] a cassette reducer adapted for being mounted in the substrate holder, the cassette reducer comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

a plurality of wafer supports joining the first substantially U-shaped plate to the second substantially U-shaped plate; and

more than two retention springs attached to the first substantially U-shaped plate for mounting the cassette reducer to the substrate holder, wherein when mounted to the holder, the cassette reducer effects a reduction in the substrate holder enabling the holder to hold another substrate smaller than the predetermined size.

2. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 1, wherein the first substantially U-shaped plate has a pair of interior arm

cutouts.

3. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 1, wherein the first substantially U-shaped plate has a base cutout.

4. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 1, wherein the holder is a front opening unified pod, and a base to tip distance of the first substantially U-shaped plate is less than an interior depth of [[a]] the front opening unified pod to which the semiconductor cassette reducer is adapted to be mated.

5. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 1, wherein the plurality of wafer supports includes a pair of side panels connected to a pair of arms of the first substantially U-shaped plate[[s]].

6. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 5, wherein the pair of side panels have a plurality of lips.

7. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 1, wherein the first substantially U-shaped plate has an exterior partial S-

shaped cutout.

8. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 1, wherein the plurality of wafer supports includes a pair of columns.

9. (Currently Amended) The [[semiconductor cassette reducer]] apparatus of claim 8, wherein the pair of columns have at least two positions.

10. (Currently Amended) A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate having a first pair of arms each having a first arm cutout;

a second substantially U-shaped plate having a second pair of arms each having a second arm cutout;

a plurality of wafer supports [[longitudinally]] connecting the first substantially U-shaped plate to the second substantially U-shaped plate; and

at least one resiliently flexible retention member mounted on at least one of the first substantially U-shaped plate or the second substantially U-shaped plate, and projecting outward beyond [[laterally from]] a lateral peripheral edge of the at least one of the first

substantially U-shaped plate or the second substantially U-shaped plate.

11. (Currently Amended) The semiconductor cassette reducer of claim 10,

[[, further including]] wherein the at least one resiliently flexible retention member comprises a plurality of retention springs attached to the first substantially U-shaped plate.

12. (Currently Amended) The semiconductor cassette reducer of claim 11, wherein one of the plurality of retention springs is designed to mate with a lip of a front opening unified pod to which the semiconductor cassette reducer is adapted to be mated.

13. (Original) The semiconductor cassette reducer of claim 10, wherein the plurality of wafer supports include a wafer support panel attached to one of the first pair of arms.

14. (Currently Amended) A semiconductor cassette reducer for a substrate holder, the cassette reducer comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

a first wafer support panel attached to a first arm of the first substantially U-shaped plate and to a first arm of the second substantially U-shaped plate; and

a second wafer support panel attached to a second arm of the first substantially U-shaped plate and to a second arm of the second substantially U-shaped plate; wherein

the first substantially U-shaped plate has a retention spring projecting outward [[from]] beyond an outer lateral edge of the first substantially U-shaped plate for engaging a surface of the substrate holder when the semiconductor cassette reducer is mounted to the substrate holder.

15. (Original) The semiconductor cassette reducer of claim 14, further including a pair of column wafer supports attached to a base of the first substantially U-shaped plate and to a base of the second substantially U-shaped plate.

16. (Previously Presented) A semiconductor cassette reducer comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

a first wafer support panel attached to a first arm of the first substantially U-shaped plate and to a first arm of the second substantially U-shaped plate; and

a second wafer support panel attached to a second arm of the first substantially U-shaped plate and to a second arm of the second substantially U-shaped plate;

wherein the first substantially U-shaped plate has a plurality of flexible disks.

17. (Original) The semiconductor cassette reducer of claim 14, wherein the first substantially U-shaped plate has a pair of arms each having an interior cutout,

18. (Currently Amended) The semiconductor cassette reducer of claim 14, wherein the substrate holder is a front opening unified pod, and a base to tip distance of the first substantially U-shaped plate is less than a diameter of wafer designed for [[a]] the front opening unified pod to which the semiconductor cassette reducer is adapted to be mated.